BECE406E FPGA BASED SYSTEM DESIGN

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Syllabus

Module:1 Programmable Logic Devices

Module: 2 HDL Fundamentals

Module:3 Implementation of Arithmetic system

Module:4 FSM and memory modelling

Module:5 Synthesis and Timing Analysis

Module: 6 SoC Design

Module: 7 FPGA Applications

Reference

- Wayne Wolf, "FPGA-Based System Design, Pearson Education", 2004.
- Michael D Ciletti, "Advanced Digital Design with the Verilog HDL", Prentice Hall, 2017.

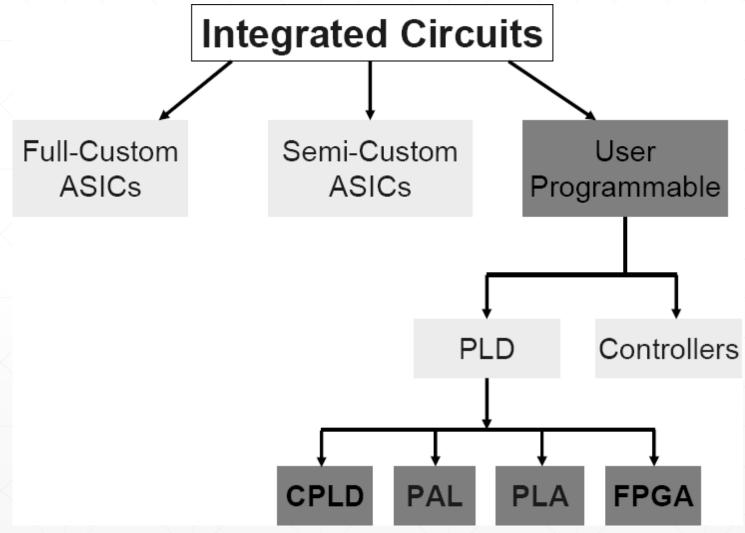
MODULE - 1

- Types of Programmable Logic Devices:
 - PLA, PAL, CPLD, FPGA
- FPGA Architecture
 - Programming Technologies
 - Chip I/O
 - Programmable Logic Blocks
 - Fabric and Architecture of FPGA

Why VLSI?

- Integration improves the design:
 - higher speed;
 - lower power;
 - physically smaller.
- Integration reduces manufacturing cost (almost) no manual assembly.

Integrated Circuits



Full Custom ICs

- Can achieve very high transistor density (transistors per square micron)
- design time can be very long (multiple months).
- Involves the creation of a completely new chip, which consists of masks (for the photolithographic manufacturing process)
- Benefits Excellent performance, small size, low power

Standard Cell

- Designer uses a library of standard cells
- an automatic place and route tool does the layout
- *Transistor density* and performance degradation depends on type of design being done.
- Design time can be much faster than full custom because layout is automatically generated.

Gate Array

- Designer uses a library of standard cells.
- The design is mapped onto an array of transistors which is already created on a wafer
- wafers with transistor arrays can be created ahead of time
- A *routing tool* creates the masks for the routing layers and "customizes" the precreated gate array for the user's design
- Transistor density can be almost as good as standard cell.
- Design time advantages are the same as for standard cell.

Semi-custom ICs

- Flexible as portion of the IC is customized by the user
- Suitable for specific applications
- Gate array + standard cell
- Paves way for application specific ICs (ASIC)

Role of FPGA

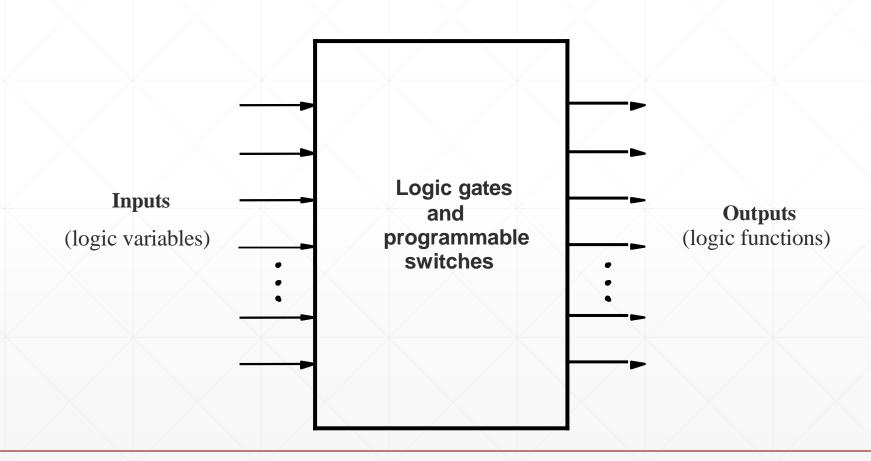
- Microprocessors used in variety of environments
 - Rely on software to implement functions
 - Generally slower and more power-hungry than custom chips
- When FPGAs?
 - Design economics
 - Shortest time to market
 - Lowest NRE cost
 - Highest unit cost
 - Make quick grab for market share
 - Same FPGA reused in several designs
 - Excellent prototyping, prototype to product --- much simple & easy to negotiate

Programmable logic devices

- Programmable Logic Device (PLD)
 - In market since 1970s.
 - An integrated circuit chip that can be configured by end user to implement different digital hardware.
 - Uses two-level logic structures to implement programmed logic.
 - First level AND plane (fixed), Second level OR plane (programmable)
 - Generally programmed by antifuses (large voltages to make connections)
 - Relatively useful for small logic functions.
 - For large logic functions, multi-level logic is essential.

PLD

PLD as a Black Box

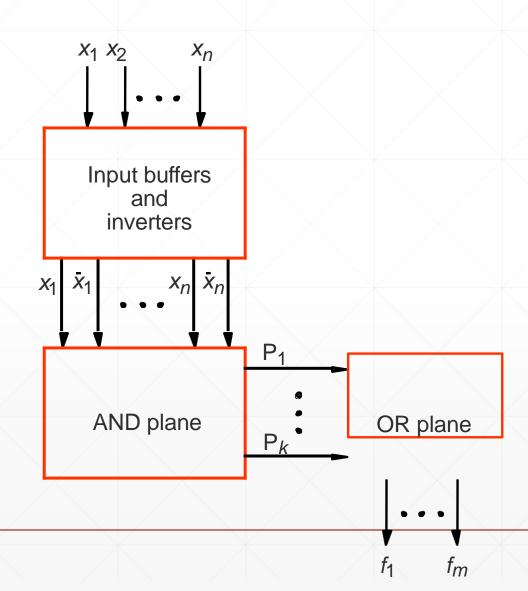


Programmable Logic Array (PLA)

Use to implement circuits in SOP form

The connections in the AND plane are programmable

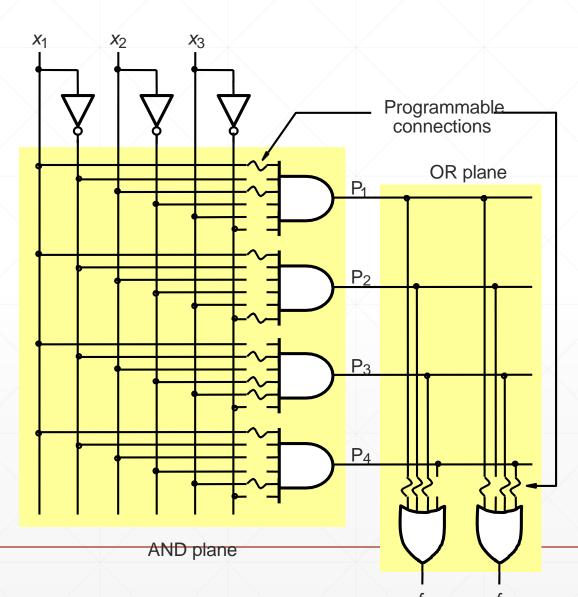
The connections in the OR plane are programmable



Gate Level Version of PLA

$$f_1 = x_1 x_2 + x_1 x_3' + x_1' x_2' x_3$$

$$f_2 = x_1x_2 + x_1'x_2'x_3 + x_1x_3$$

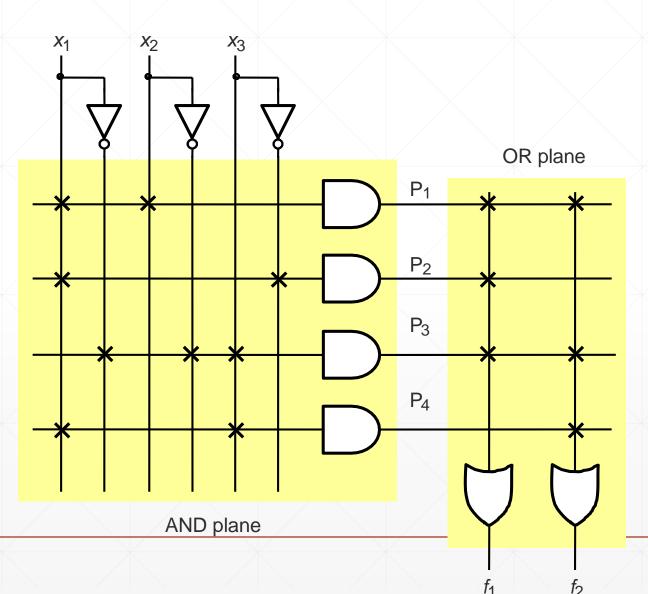


Customary Schematic of a PLA

$$f_1 = x_1x_2 + x_1x_3' + x_1'x_2'x_3$$

$$f_2 = x_1 x_2 + x_1' x_2' x_3 + x_1 x_3$$

x marks the connections left in place after programming



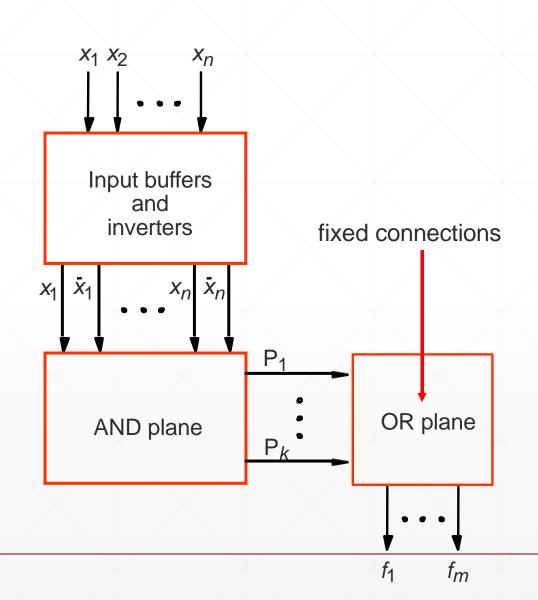
Limitations of PLAs

- Typical size is 16 inputs, 32 product terms, 8 outputs
 - Each AND gate has large fan-in this limits the number of inputs that can be provided in a PLA
 - 16 inputs 2¹⁶ = possible input combinations; only 32 permitted (since 32 AND gates) in a typical PLA
 - 32 AND terms permitted large fan-in for OR gates as well
- This makes PLAs slower and slightly more expensive than some alternatives to be discussed shortly

Programmable Array Logic (PAL)

- Also used to implement circuits in SOP form
- The connections in the AND plane are programmable

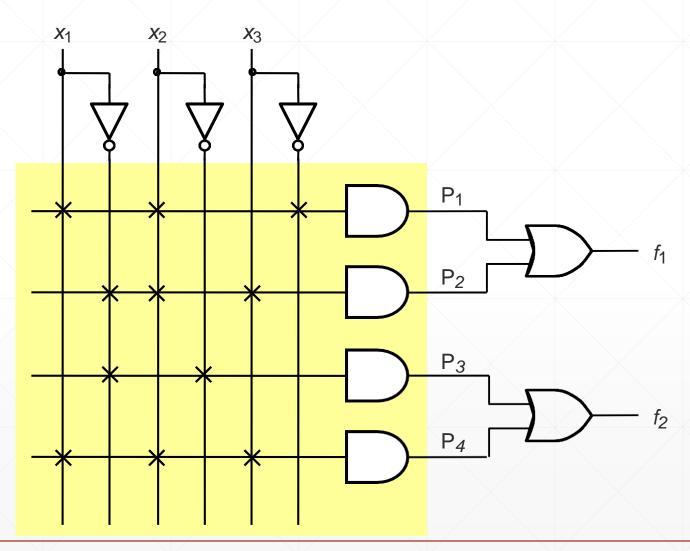
 The connections in the OR plane are <u>NOT</u> programmable



Example Schematic of a PAL

$$f_1 = x_1x_2x_3' + x_1'x_2x_3$$

 $f_2 = x_1'x_2' + x_1x_2x_3$

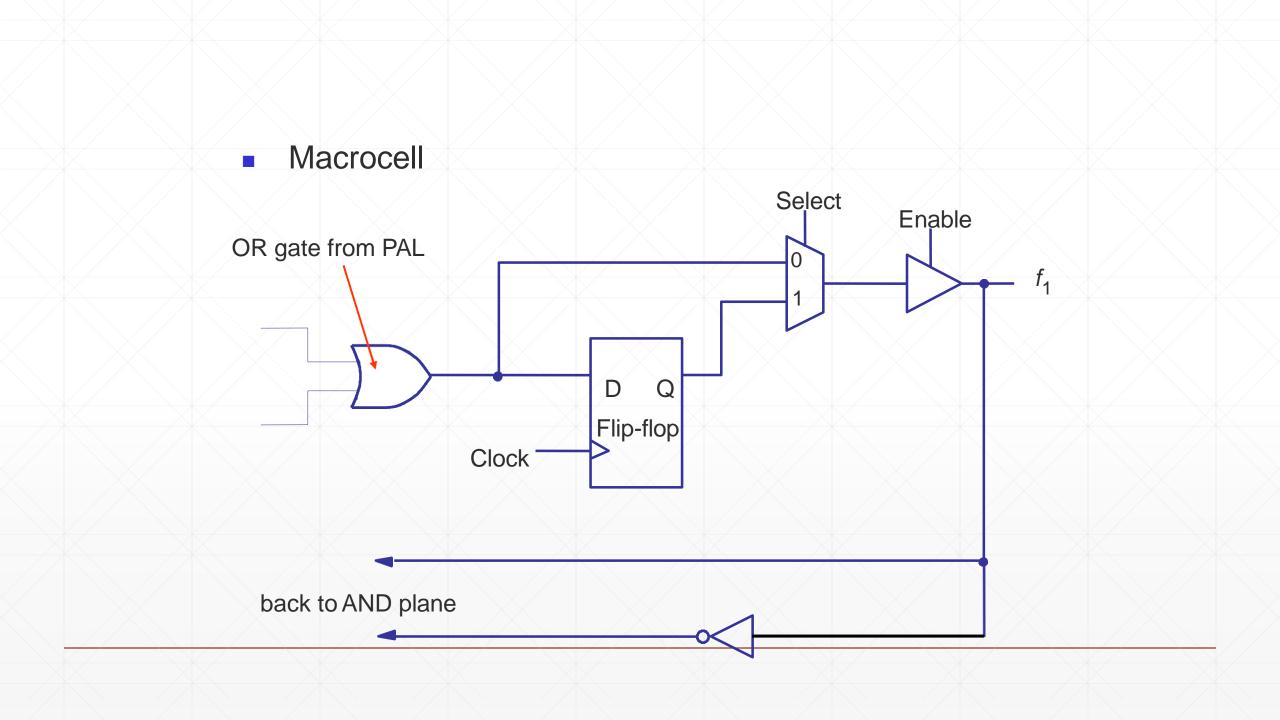


Comparing PALs and PLAs

PALs have the same limitations as PLAs (small number of allowed AND terms)
 plus they have a fixed OR plane □ less flexibility than PLAs

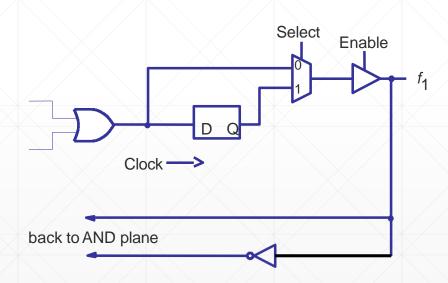
PALs are simpler to manufacture, cheaper, and faster (better performance)

- PALs also often have extra circuitry connected to the output of each OR gate
 - The OR gate plus this circuitry is called a macrocell



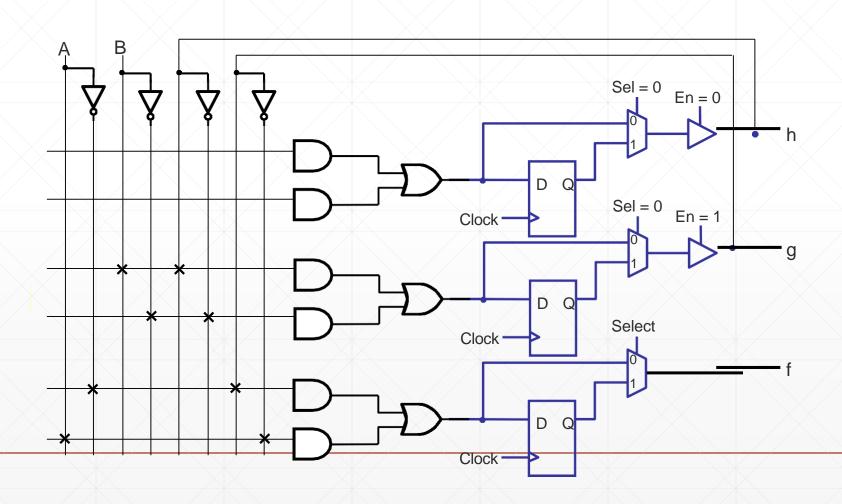
Macrocell Functions

- Enable = 0 can be used to allow the output pin for f_1 to be used as an additional input pin to the PAL.
- Enable = 1, Select = 0 is normal for typical PAL operation.
- Enable = Select = 1 allows the PAL to synchronize the output changes with a clock pulse.
- The feedback to the AND plane provides for multi-level design

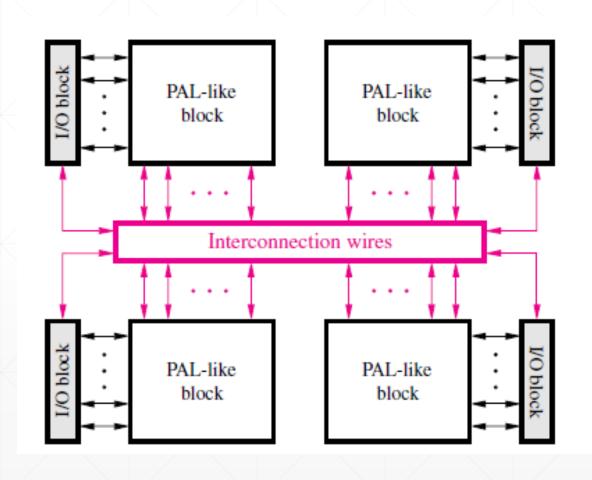


Multi-Level Design with PALs

- f = A'BC + A'B'C' + ABC' + AB'C = A'g + Ag'
 - where g = BC + B'C' and C = h below

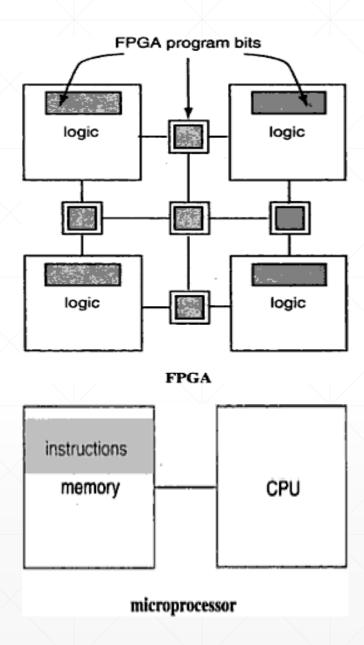


Complex Programmable Logic Devices (CPLDs)



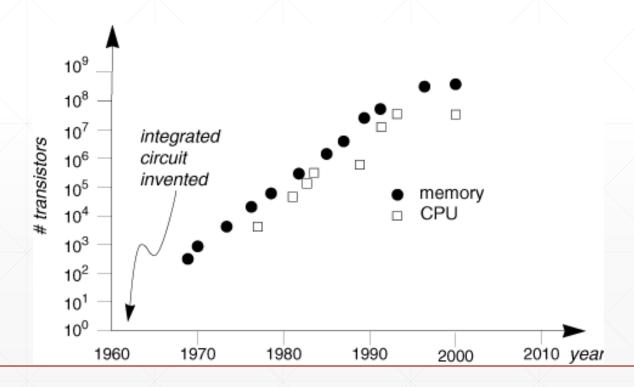
FPGA Programming

- FPGAs implement multi-level logic
- Need both programmable logic blocks and programmable interconnect
- Combination of logic and interconnect is fabric
- Microprocessor is a stored-program computer



Moore's Law

- Gordon Moore: co-founder of Intel.
- Predicted that number of transistors per chip would grow exponentially (double every 18 months).



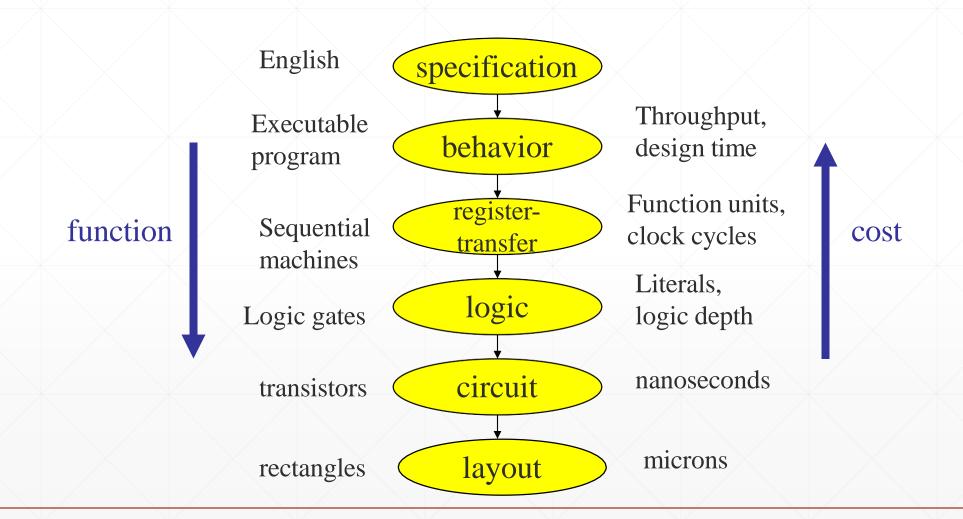
Goals and Techniques

- Performance
 - Logic run at a required rate
 - Throughput, Latency, Clock rate performance measures
- Power/energy
- Design time
 - FPGAs are standard cells
 - Prototypes can be programmed quickly
- Design cost
 - FPGA tools less expensive than custom VLSI tools
- Manufacturing cost
 - Cost of replicating the system many times
 - FPGAs are relatively high cost than ASICs

Design Challenges

- Multiple levels of abstraction
- Power consumption
- Short design time

FPGA Abstractions



- Top-down design adds functional detail.
 - Create lower levels of abstraction from upper levels.
- Bottom-up design creates abstractions from low-level behavior.
 - More accurate delay information.
- Good design needs cycles of top-down approach followed by bottomup efforts.

Methodology

- Hardware Description logic (HDL)
 - VHDL
 - VerilogHDL
- Synthesis Tool

Major FPGA Vendors

- SRAM-based FPGAs
 - Xilinx, Inc

Share 80% of the market

- Altera Corp.
- Atmel
- Lattice Semiconductor
- Flash & Antifuse FPGAs
 - Actel Corp.
 - Quick logic Corp.

FPGA Vendors and Device families

- Xilinx
 - Spartan
 - Virtex
 - Kintex
 - Artix
- Altera
 - Stratix
 - Cyclone
 - MAX 3000/7000 CPLD
 - MAX-II

Xilinx Families

Old families

- XC3000, XC4000, XC5200
- Old 0.5µm, 0.35µm and 0.25µm technology. Not recommended for modern designs.

High-performance families

- Virtex (0.22µm)
- Virtex-E, Virtex-EM (0.18µm)
- Virtex-II, Virtex-II PRO (0.13µm)
- Virtex-4 (0.09µm)

Low Cost Family

- Spartan/XL derived from XC4000
- Spartan-II derived from Virtex
- Spartan-IIE derived from Virtex-E
- Spartan-3 derived from Virtex-II

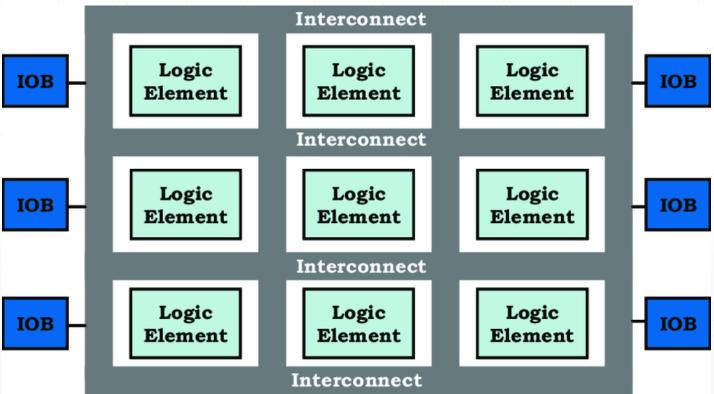
Altera Families

- Old Families
 - FLEX 10K, FLEX 6000, FLEX 8000
- High-performance Families
 - Mercury
 - Stratix, Stratix GX, Stratix II
 - APEX 20K, APEX II
 - Excalibur
- Low Cost Family
 - Cyclone, Cyclone II

FPGA FABRICS

3 major types of elements

- Combinational logic
- Interconnect
- I/O pins



- Combinational logic
- The combinational logic is divided into relatively small units which may be known as logic elements (LEs) or combinational logic blocks (CLBs).
- The LE or CLB can usually form the function of several typical logic gates but it is still small compared to the typical combinational logic block found in a large design.

• Interconnects:

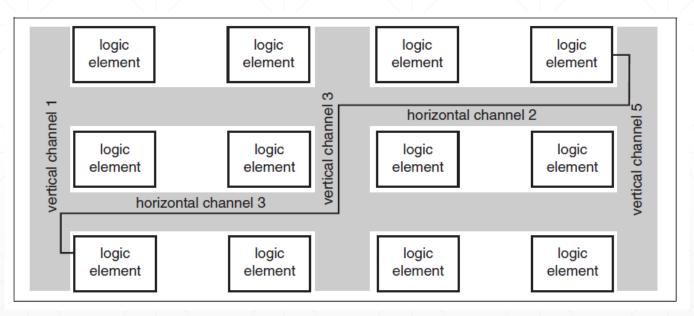
- The interconnections are made between the logic elements using programmable interconnect.
- The interconnect may be logically organized into channels or other units.
- FPGAs typically offer several types of interconnect depending on the distance between the combinational logic blocks that are to be connected; clock signals are also provided with their own interconnection networks.

- I/O pins:
- The I/O pins may be referred to as I/O blocks (IOBs).
- They are generally programmable to be inputs or outputs and often provide other features such as low-power or high-speed connections.

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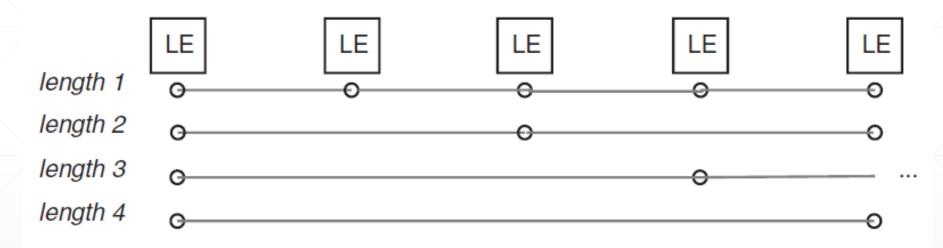
FPGA interconnect

- An FPGA designer must rely on predesigned wiring, unlike a custom VLSI designer.
- LEs are arranged in some sort of 2D structure, so interconnect may require complex paths.
- Wires are typically organized in wiring channels or routing channels that run horizontally and vertically through the chip.
- Connections must be made between wires in order to carry a signal from one point to another.



Segmented wiring

• FPGA channels provide wires of a variety of lengths.

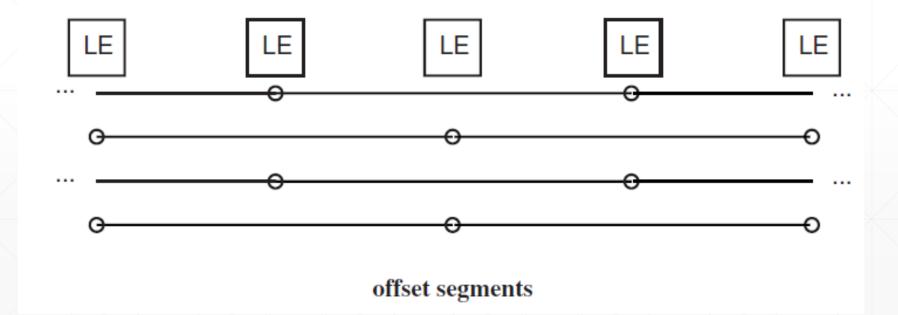


segments of varying lengths

- The figure shows connections of varying length as measured in units of LEs:
 - the top signal of length 1 goes to the next LE,
 - the second signal goes to the second LE, and so on

Offset wiring

- The alternative to segmented wiring is to make each wire length 1.
- The segment in a group need not all end at one point.



FPGA configuration

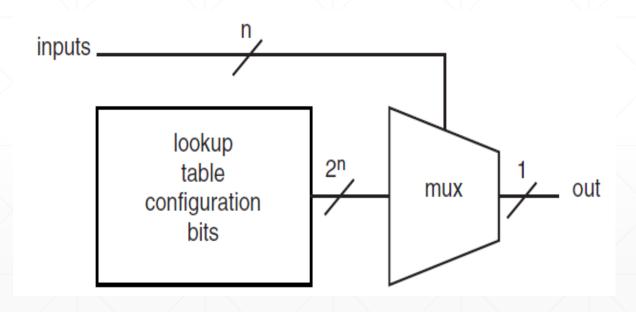
- 3 major circuit technologies for configuring an FPGA:
 - SRAM
 - Antifuse
 - Flash
- Characteristics of interest to the system designer:
 - How much logic can I fit into this FPGA?
 - How many I/O pins does it have?
 - How fast does it run?

SRAM-Based FPGAs

- Characteristics of SRAM-based FPGAs
 - SRAM-based FPGAs hold their configurations in static memory
 - The output of the memory cell is directly connected to another circuit and the state of the memory cell continuously controls the circuit being configured.
- Advantages:
 - FPGA can be easily reprogrammed
 - dynamically reconfigurable systems
 - fabricated with standard VLSI processes
- Disadvantages: Power & Security
- Each combinational logic element requires many programming bits.
- Each programmable interconnection point requires its own bit.

Logic Elements

- The basic method used to build a combinational logic block (CLB)— also called a logic element or LE—in an SRAM-based FPGA is the lookup table (LUT).
- LUT is an SRAM that is used to implement a truth table.
- Each address in the SRAM represents a combination of inputs to the logic element.
- The value stored at that address represents the value of the function for that input combination.

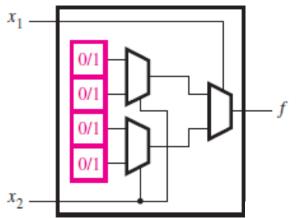


LUT

Logic Elements

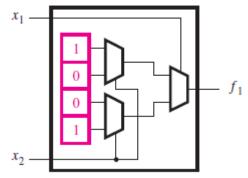
- An n-input function requires an SRAM with 2ⁿ locations.
- A basic SRAM is not clocked --- as its inputs change, its output changes after some delay.
- A typical logic element has four inputs.
- The delay through the lookup table is independent of the bits stored in the SRAM, so the delay through the logic element is the same for all functions.
- For example, a lookup table based LE will exhibit the same delay for a 4-input XOR and a 4-input NAND.

Circuit for a two-input LUT

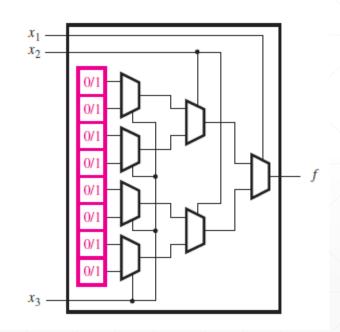


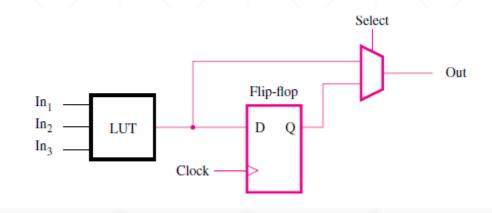
x_1	x_2	f_1
0	0	1
0	1	0
1	0	0
1	1	1

(b)
$$f_1 = \bar{x}_1 \bar{x}_2 + x_1 x_2$$

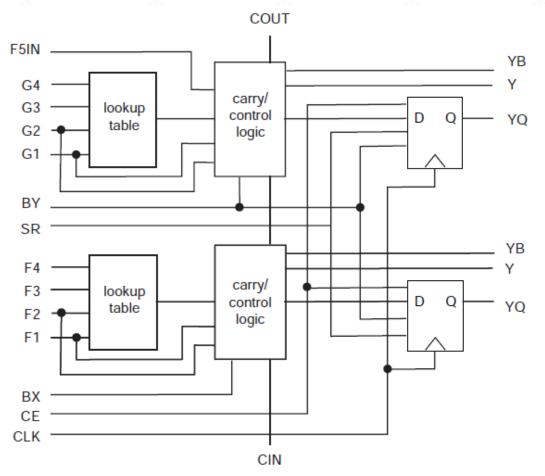


A three-input LUT





Xilinx Spartan-II CLB

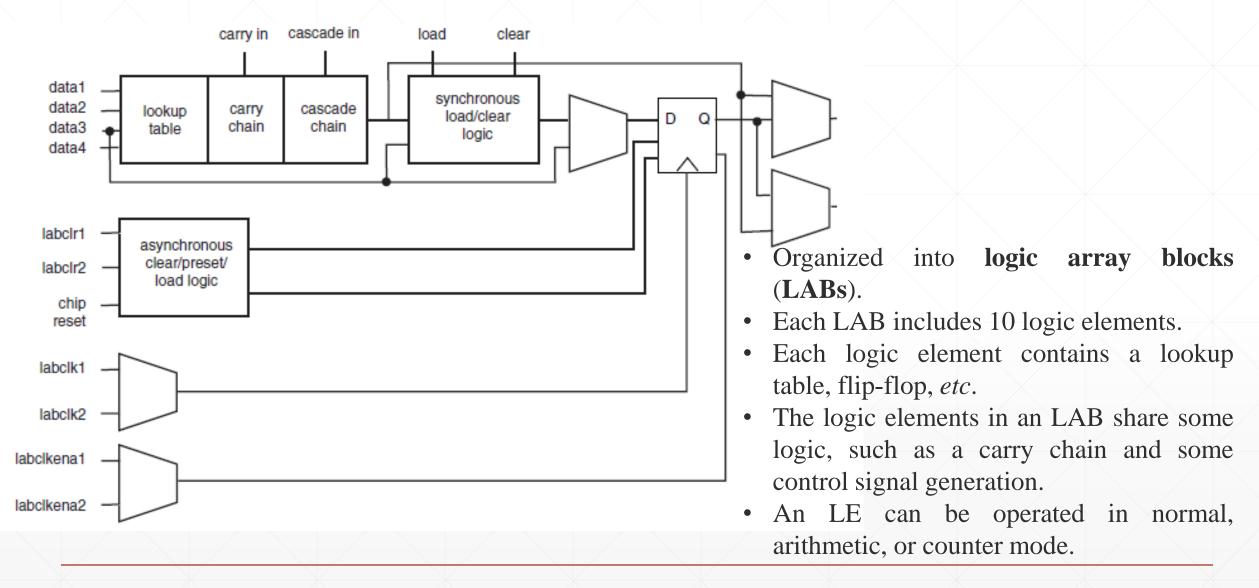


- Consists of two identical slices, with each slice containing a LUT, some carry logic, and registers
- A slice includes two logic cells (LCs).
- The foundation of a logic cell is the pair of four-bit lookup tables.
- Their inputs are F1-F4 and G1-G4.
- Each lookup table can also be used as a 16-bit synchronous
 RAM or as a 16-bit shift register.

Xilinx Spartan-II CLB

- Each slice also contains carry logic for each LUT so that additions can be performed.
- A carry in to the slice enters the CIN input, goes through the two bits of carry chain, and out through COUT.
- Each slice includes a multiplexer that is used to combine the results of the two function generators in a slice.
- Another multiplexer combines the outputs of the multiplexers in the two slices, generating a result for the entire CLB.
- The registers can be configured either as D-type flip-flops or as latches.
- Each register has clock and clock enable signals.
- Each CLB also contains two three-state drivers (known as BUFTs) that can be used to drive on-chip busses.

Altera APEX II logic elements



Logic Elements

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- For example, a lookup table based LE will exhibit the same delay for a 4-input XOR and a 4-input NAND.

Interconnection Networks

- An SRAM-based FPGA uses SRAM to hold the information used to program the interconnect.
- As a result, the interconnect can be reconfigured, just as the logic elements can.
- Figure shows a simple version of an interconnection point,
 - often known as a connection box.
- A programmable connection between two wires is made by a CMOS transistor (a pass transistor).
- The pass transistor's gate is controlled by a static memory program bit (shown here as a D register).

Interconnection Networks

- When the pass transistor's gate is high, the transistor conducts and connects the two wires.
- When the gate is low, the transistor is off and the two wires are not connected.
- The transistor also conducts bidirectionally.
- Pass transistor is relatively slow.
- Alternative circuits (mostly unidirectional) provide higher performance at the cost of additional chip area.

Types of programmable interconnect

- An FPGA requires a large number of programmable wires in order to take advantage of the logic in the LEs.
- Wiring is often organized into different categories depending on its structure and intended use.
- Short wires connect only local LEs.
 - These wires don't take up much space and they introduce less delay.
 - The carry chains through the LEs are one example of short interconnect.

Global wires

- designed for long-distance communications with high-speed highways
- they have fewer connection points than local connections
- repeaters to reduce the effects of delay
- Special wires may be dedicated to distribute clocks or other register control signals.

The Xilinx Spartan-II interconnect system

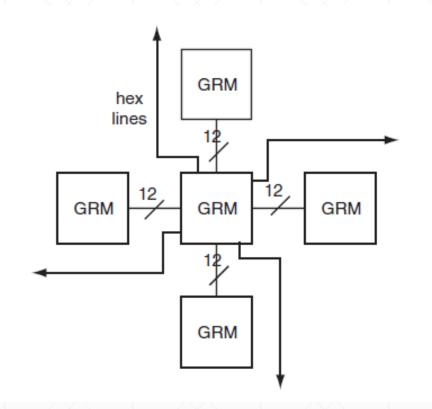
- The **Spartan-II** includes several types of interconnect:
 - local
 - general purpose
 - I/O
 - global
 - clock

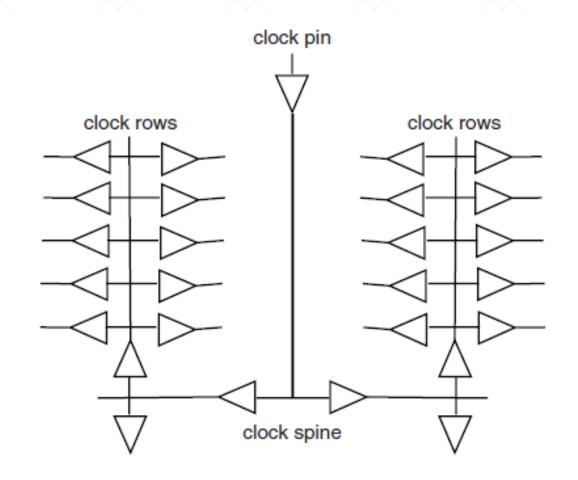
• Local interconnect :

- It connects the LUTs, flip-flops, and general purpose interconnect.
- It also provides internal CLB feedback.
- Finally, it includes some direct paths for high-speed connections between horizontally adjacent CLBs.
- These paths can be used for arithmetic, shift registers, or other functions that need structured layout and short connections.

The Xilinx Spartan-II interconnect system

- The general-purpose routing network provides the bulk of the routing resources.
- This network includes several types of interconnect:
 - A general routing matrix (GRM) is a switch matrix used to connect horizontal and vertical routing channels as well as the connections between the CLBs and the routing channels.
 - There are 24 single-length lines to connect each GRM to the four nearest GRMs, to the left, right, above, and below.
 - Hex lines route GRM signals to the GRMs six blocks away. Hex lines provide longer interconnect. The hex lines include buffers to drive the longer wires. There are 96 hex lines, one third bidirectional and the rest unidirectional.
 - 12 longlines provide interconnect spanning the entire chip, both vertically and horizontally.

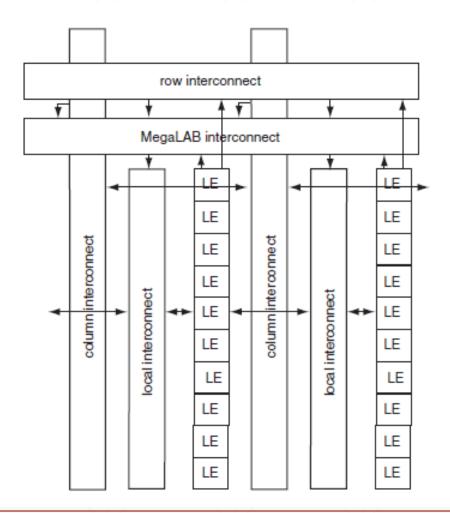




The clock distribution network is buffered to provide low delay and low skew

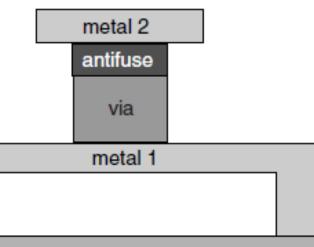
The Altera APEX II interconnect system

- The APEX II uses horizontal and vertical interconnect channels to interconnect the logic elements and the chip pins.
- A row line can be driven directly by an LE, I/O element, or embedded memory in that row.
- A column line can also drive a row line; columns can be used to connect wires in two rows.
- Some dedicated signals with buffers are provided for highfanout signals such as clocks.
- Column I/O pins can directly drive these interconnect lines.
- Each line traverses two MegaLAB structures, driving the four MegaLABs in the top row and the four MegaLABs in the bottom row of the chip.



Antifuses

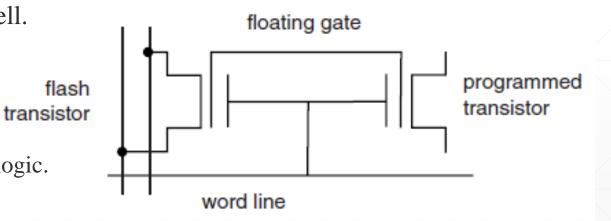
- An antifuse, as shown in Figure, is fabricated as a normally open disconnection.
- When a programming voltage is applied across the antifuse, it makes a connection between the metal line above it and the via to the metal line below.
- An antifuse has a resistance on the order of 100 Ω , which is more resistance than a standard via.
- The antifuse has several advantages over a fuse, a major one being that most connections in an FPGA should be open, so the antifuse leaves most programming points in the proper state.
- An antifuse is programmed by putting a voltage across it.
- Each antifuse must be programmed separately.
- The FPGA must include circuitry that allows each antifuse to be separately addressed and the programming voltage applied.



substrate

Flash Configuration

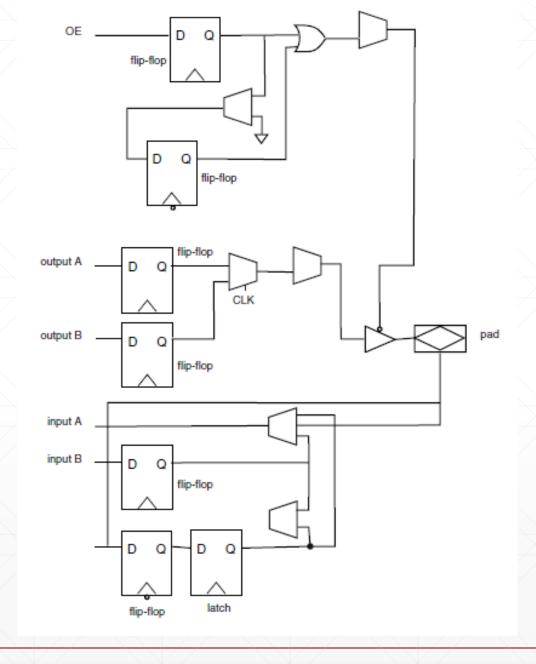
- Flash memory is a high-quality programmable read-only memory.
- Flash uses a floating gate structure in which a low-leakage capacitor holds a voltage that controls a transistor gate.
- This memory cell can be used to control programming transistors.
- Figure shows the schematic of a flash-programmed cell.
- The memory cell controls two transistors.
- One is the programmable connection point.
 - used for interconnect electrical nodes in interconnect or logic.
- The other allows read-write access to the cell.



Chip I/O

- The I/O pins on a chip connect it to the outside world. The I/O pins on any chip perform some basic functions:
- Input pins provide electrostatic discharge (ESD) protection.
- Output pins provide buffers with sufficient drive to produce adequate signals on the pins.
- Three-state pins include logic to switch between input and output modes.
- The pins on an FPGA must be programmable to accommodate the requirements of the configured logic.
- A standard FPGA pin can be configured as either an input, output, or three-state pin.

Altera APEX-II I/O pin



The Xilinx Spartan-II 2.5V I/O pin

